

Ultrafast Soft Recovery Diode, 150 A FRED Pt[®]


 PowerTab[®]


FEATURES

- Ultrafast recovery time
- 175 °C max. operating junction temperature
- Screw mounting only
- Designed and qualified according to JEDEC-JESD47
- Compliant to RoHS Directive 2002/95/EC
- PowerTab[®] package


 RoHS
COMPLIANT

BENEFITS

- Reduced RFI and EMI
- Higher frequency operation
- Reduced snubbing
- Reduced parts count

DESCRIPTION/APPLICATIONS

These diodes are optimized to reduce losses and EMI/RFI in high frequency power conditioning systems. The softness of the recovery eliminates the need for a snubber in most applications. These devices are ideally suited for HF welding, power converters and other applications where switching losses are not significant portion of the total losses.

PRODUCT SUMMARY	
Package	PowerTab [®]
I _F (AV)	150 A
V _R	400 V
V _F at I _F	1.3 V
t _{rr} (typ.)	See recovery table
T _J max.	175 °C
Diode variation	Single die

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS
Cathode to anode voltage	V _R		400	V
Continuous forward current	I _{F(AV)}	T _C = 104 °C	150	A
Single pulse forward current	I _{FSM}	T _C = 25 °C	1500	
Maximum repetitive forward current	I _{FRM}	Square wave, 20 kHz	300	
Operating junction and storage temperatures	T _J , T _{Stg}		- 55 to 175	°C

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	V _{BR} , V _R	I _R = 200 μA	400	-	-	V
Forward voltage	V _F	I _F = 150 A	-	1.07	1.3	
		I _F = 150 A, T _J = 175 °C	-	0.9	1.1	
		I _F = 150 A, T _J = 125 °C	-	0.96	1.17	
Reverse leakage current	I _R	V _R = V _R rated	-	-	50	μA
		T _J = 150 °C, V _R = V _R rated	-	-	4	mA
Junction capacitance	C _T	V _R = 400 V	-	100	-	pF
Series inductance	L _S	Measured lead to lead 5 mm from package body	-	3.5	-	nH



DYNAMIC RECOVERY CHARACTERISTICS ($T_J = 25\text{ }^\circ\text{C}$ unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Reverse recovery time	t_{rr}	$I_F = 1.0\text{ A}$, $di_F/dt = 200\text{ A}/\mu\text{s}$, $V_R = 30\text{ V}$	-	-	60	ns
		$T_J = 25\text{ }^\circ\text{C}$	-	93	-	
		$T_J = 125\text{ }^\circ\text{C}$	-	172	-	
Peak recovery current	I_{RRM}	$T_J = 25\text{ }^\circ\text{C}$	-	11	-	A
		$T_J = 125\text{ }^\circ\text{C}$	-	20	-	
Reverse recovery charge	Q_{rr}	$T_J = 25\text{ }^\circ\text{C}$	-	490	-	nC
		$T_J = 125\text{ }^\circ\text{C}$	-	1740	-	

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Thermal resistance, junction to case	R_{thJC}		-	-	0.35	K/W
Thermal resistance, junction to heatsink	R_{thCS}	Mounting surface, flat, smooth and greased	-	0.2	-	
Weight			-	-	5.02	g
			-	0.18	-	oz.
Mounting torque			1.2 (10)	-	2.4 (20)	N · m (lb · in)
Marking device		Case style PowerTab®	150EBU04			

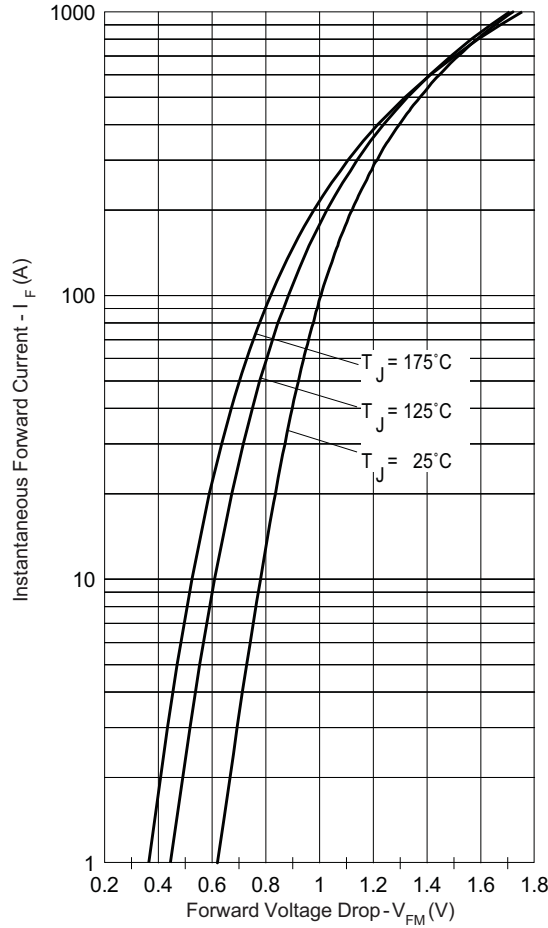


Fig. 1 - Maximum Forward Voltage Drop Characteristics

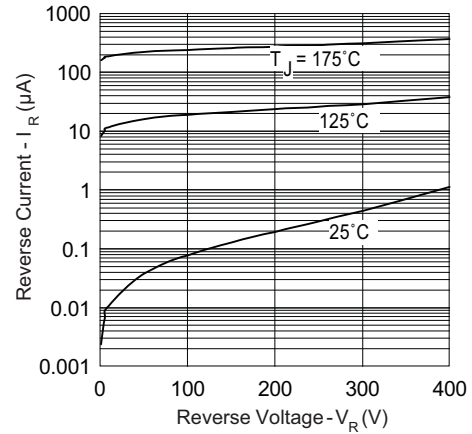


Fig. 1 - Typical Values of Reverse Current vs. Reverse Voltage

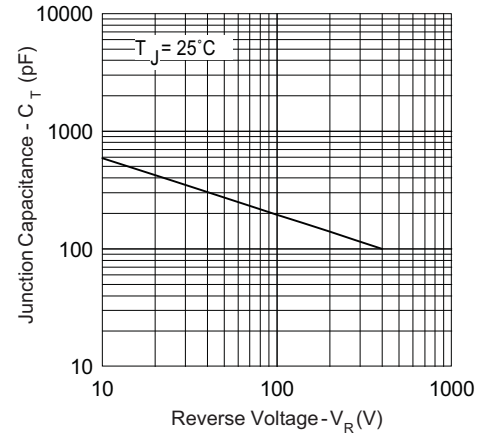


Fig. 2 - Typical Junction Capacitance vs. Reverse Voltage

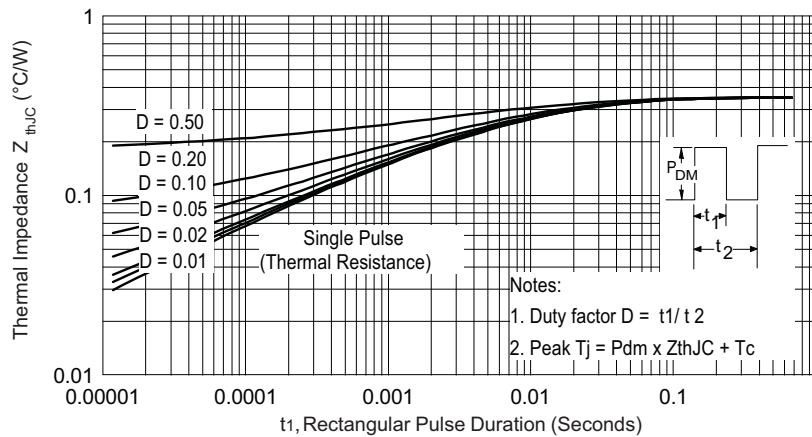


Fig. 2 - Maximum Thermal Impedance Z_{thJC} Characteristics

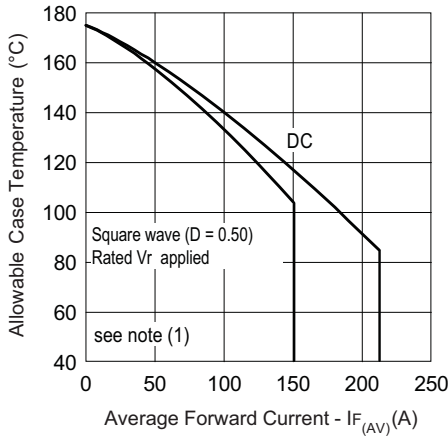


Fig. 3 - Maximum Allowable Case Temperature vs. Average Forward Current

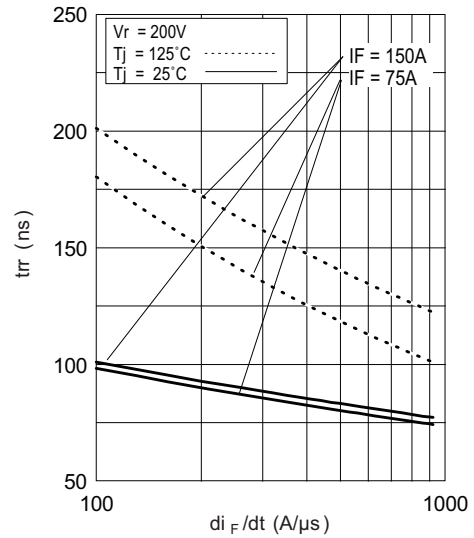


Fig. 4 - Typical Reverse Recovery Time vs. di_F/dt

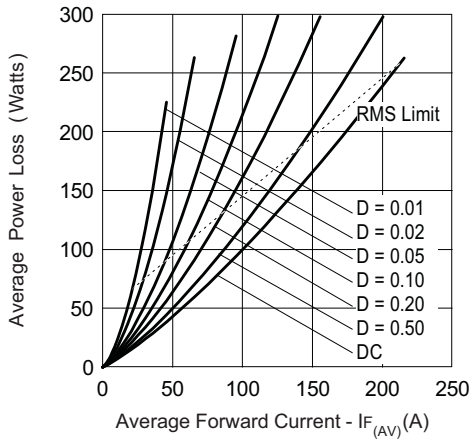


Fig. 3 - Forward Power Loss Characteristics

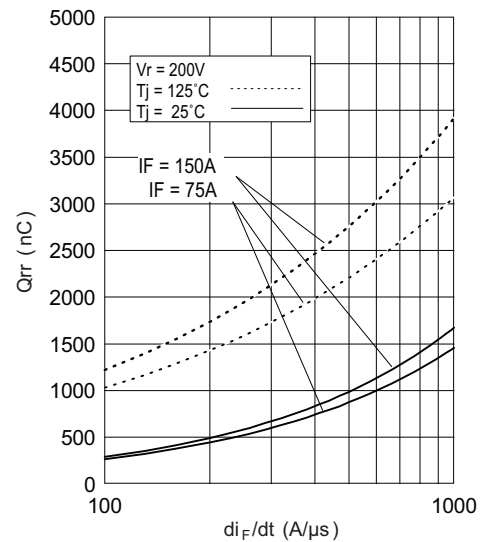


Fig. 5 - Typical Stored Charge vs. di_F/dt

Note

- (1) Formula used: $T_C = T_J - (P_d + P_{d_{REV}}) \times R_{thJC}$;
 P_d = Forward power loss = $I_{F(AV)} \times V_{FM}$ at $(I_{F(AV)}/D)$ (see fig. 6);
 $P_{d_{REV}}$ = Inverse power loss = $V_{R1} \times I_R (1 - D)$; I_R at V_{R1} = Rated V_R

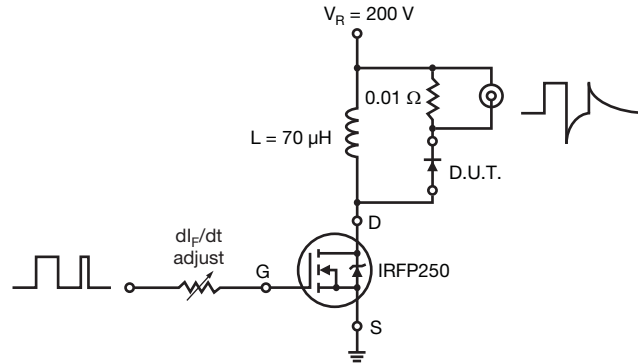
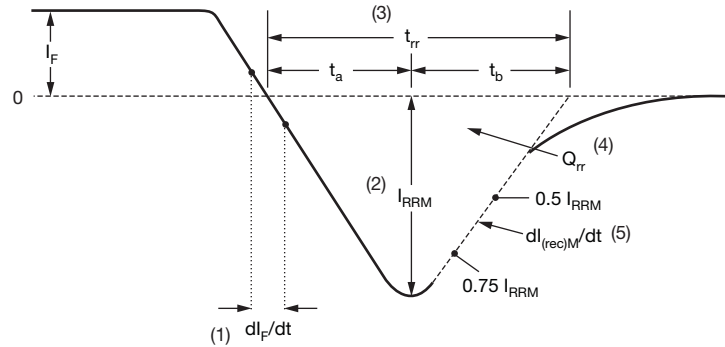


Fig. 9 - Reverse Recovery Parameter Test Circuit



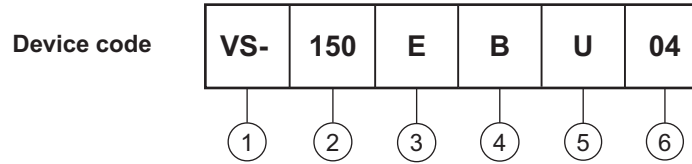
- (1) di_F/dt - rate of change of current through zero crossing
- (2) I_{RRM} - peak reverse recovery current
- (3) t_{rr} - reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through $0.75 I_{RRM}$ and $0.50 I_{RRM}$ extrapolated to zero current.
- (4) Q_{rr} - area under curve defined by t_{rr} and I_{RRM}
- (5) $di_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

Fig. 10 - Reverse Recovery Waveform and Definitions



ORDERING INFORMATION TABLE



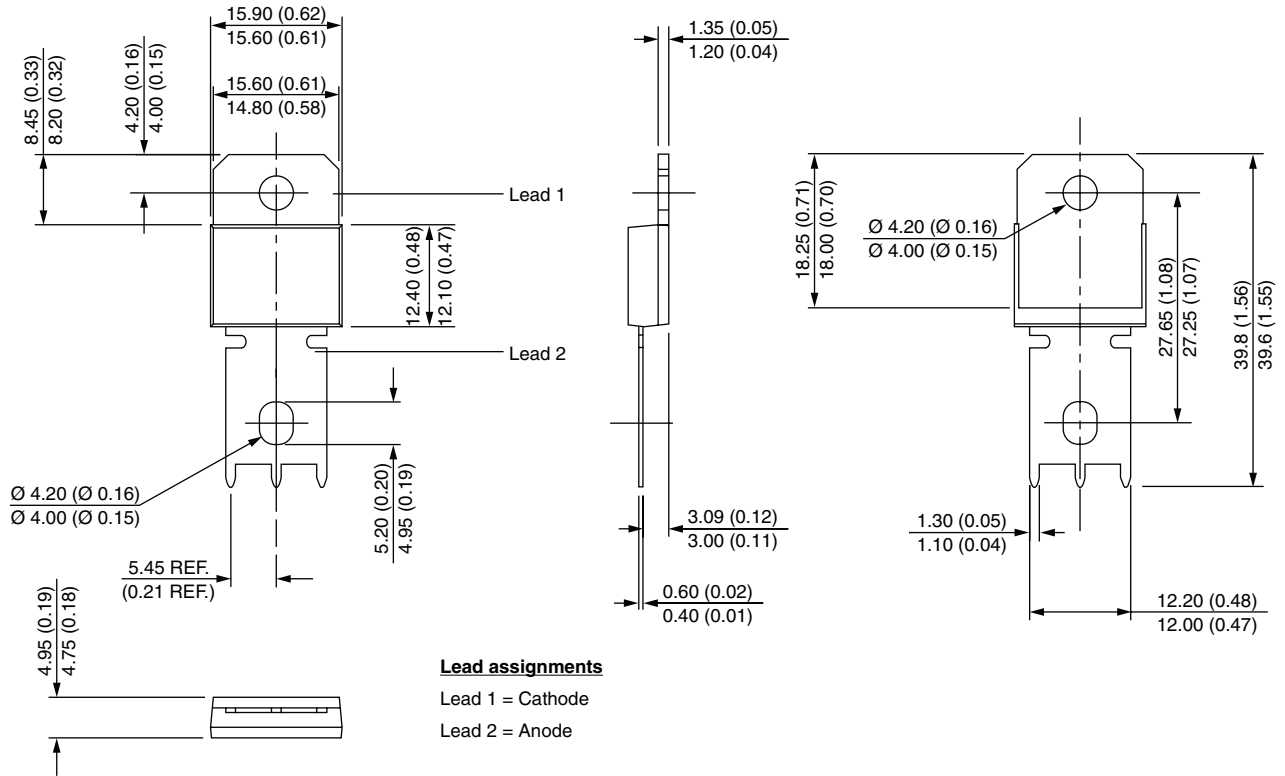
- 1** - Vishay Semiconductors product
- 2** - Current rating (150 = 150 A)
- 3** - Single diode
- 4** - PowerTab® (ultrafast/hyperfast only)
- 5** - Ultrafast recovery
- 6** - Voltage rating (04 = 400 V)

LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?95240
Part marking information	www.vishay.com/doc?95370
Application note	www.vishay.com/doc?95179



PowerTab™

DIMENSIONS in millimeters (inches)





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